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## 18V/3A Step-Down DC/DC Converter

### FEATURES

- 3A Output Current
- Wide 4.5V to 18V Operating Input Range
- Synchronous Buck Topology
- Integrated 85mΩ Power MOSFET Switches
- Output Adjustable from 0.923V to 12V
- Up to 96% Efficiency
- Stable with Low ESR Ceramic Output Capacitors
- Internal Soft Start
- 3mA Low Standby Input Current
- High Light Load Efficiency
- Cycle-by-Cycle Over Current Limit
- Input Under Voltage Lockout
- Hiccup Protection at Short Circuit and Over Current
- Frequency Fold Back Protection
- Low Power Dissipation at Over Current and Short Circuit

### GENERAL DESCRIPTION

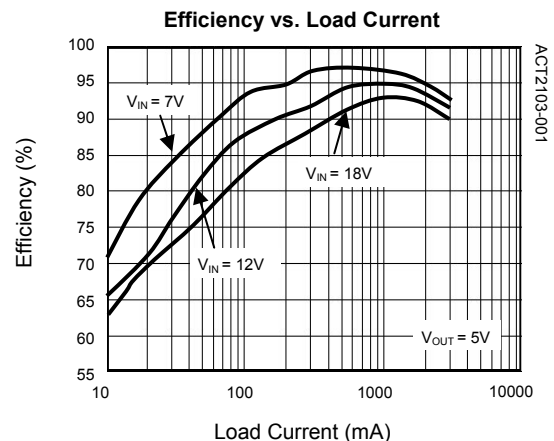
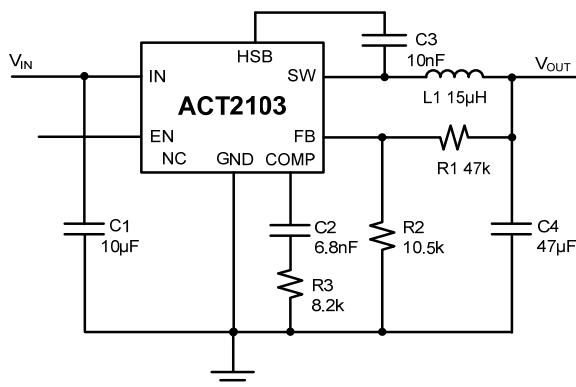
ACT2103 is a monolithic synchronous buck regulator. The device integrates two 85mΩ MOSFETs, and provides 3A of continuous load current over a wide input voltage of 4.5V to 18V. Current mode control provides fast transient response and cycle-by-cycle current limit. Hiccup at short circuit reduces IC temperatures.

An internal soft-start prevents inrush current at turn-on, and in shutdown mode the supply current drops to 10μA. Pulse-skipping mode at light load reduces standby power down to 3mA.

This device, available in an 8-pin SOP-8EP package, provides a very compact solution with minimal external components.

### APPLICATIONS

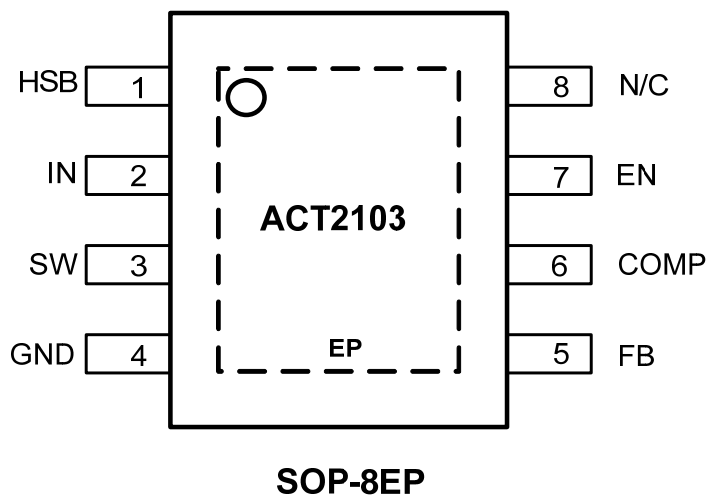
- LCD-TV
- Set-top Box
- Distributed Power Systems
- Networking Systems



## ORDERING INFORMATION

PART NUMBER	OPERATION TEMPERATURE RANGE	PACKAGE	PINS	PACKING
ACT2103YH-T	-40°C to 85°C	SOP-8EP	8	TAPE & REEL

## PIN CONFIGURATION



## PIN DESCRIPTIONS

PIN	NAME	DESCRIPTION
1	HSB	High-Side Bias Input. This pin acts as the positive rail for the high-side switch's gate driver. Connect a 10nF or greater capacitor between HSB and SW pins.
2	IN	Input Supply. Bypass this pin to GND with a low ESR capacitor. Drive IN with a 4.5V to 18V power source. See <i>Input Capacitor</i> in the <i>Application Information</i> section.
3	SW	Switch Output. Connect this pin to the switching end of the external inductor. Note that a capacitor is required from SW to HSB to power the high-side switch.
4	GND	Ground.
5	FB	Feedback Input. FB senses the output voltage to regulate that voltage. Drive FB with a resistive voltage divider from the output voltage. The feedback threshold is 0.923V. See <i>Setting the Output Voltage</i> .
6	COMP	Compensation Node. COMP is used to compensate the regulation control loop. See <i>Compensation Components</i> .
7	EN	Enable Input. When higher than 2.5V, this pin turns the IC on. When lower than 2.3V, this pin turns IC off. When left unconnected, EN is pulled up to logic HIGH with a 2μA pull-up current. EN is a digital input that turns the regulator on or off.
8	N/C	Not connected.

**ABSOLUTE MAXIMUM RATINGS<sup>①</sup>**

PARAMETER	VALUE	UNIT
IN to GND	-0.3 to + 20	V
SW to GND	-1 to VIN + 1	V
HSB to GND	$V_{SW} - 0.3$ to $V_{SW} + 6$	V
FB, EN, COMP to GND	-0.3 to + 6	V
Continuous SW Current	Internally limited	A
Junction to Ambient Thermal Resistance	46	°C/W
Maximum Power Dissipation	0.76	W
Operating Junction Temperature	-40 to 150	°C
Storage Junction	-55 to 150	°C
Lead Temperature (Soldering 10 sec.)	300	°C

①: Do not exceed these limits to prevent damage to the device. Exposure to Absolute Maximum Rating conditions for long periods may affect device reliability.



## ELECTRICAL CHARACTERISTICS

( $V_{IN} = 12V$ ,  $T_A = 25^\circ C$ , unless otherwise specified.)

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Shutdown Supply Current		$V_{EN} = 0V$		10	20	$\mu A$
Supply Current		$V_{EN} = 3V$ , $V_{FB} = 1.2V$		0.75	1.1	mA
Feedback Voltage	$V_{FB}$	$4.75V \leq V_{IN} \leq 18V$	0.909	0.923	0.937	V
Error Amplifier Voltage Gain	$A_{EA}$			400		V/V
Error Amplifier Transconductance	$G_{EA}$	$\Delta I_C = \pm 10\mu A$		800		$\mu A/V$
High-Side Switch On Resistance	$R_{DS(ON)1}$			85		m $\Omega$
Low-Side Switch On Resistance	$R_{DS(ON)2}$			85		m $\Omega$
Upper Switch Current Limit		50% Duty Cycle		4.5		A
COMP to Current Sense	$G_{CS}$			4.5		A/V
Oscillation Frequency	$F_{sw}$		280	310	340	kHz
Short Circuit Oscillation Frequency				80		kHz
Maximum Duty Cycle	$D_{MAX}$			88		%
EN Lockout Threshold Voltage			2.4	2.6	2.8	V
EN Lockout Hysteresis				75		mV
Input Under Voltage Lockout Threshold		Input Voltage Rising	4	4.2	4.4	V
Internal Soft Startup Time				2		ms
Hiccup Frequency at short circuit				26		Hz
Under Voltage Threshold				0.74		V
Thermal Shutdown				160		$^\circ C$
Thermal Shutdown Hysteresis Window				30		$^\circ C$



## Secondary Over Current Protection (SOCP)

In normal operation, ACT2103 high-side FET current is protected by cycle-by-cycle current limit. In some fault conditions, the input current may run away. SOCP current limit is set 30% higher than cycle-by-cycle current limit, and once SOCP is triggered, ACT2103 goes into hiccup mode and reduce the power dissipation significantly.

## Enable Pin

The ACT2103 has an enable input EN for turning the IC on or off. The EN pin contains a precision 2.5V comparator with 75mV hysteresis and a 1.3 $\mu$ A pull-up current source. The comparator can be used with a resistor divider from  $V_{IN}$  to program a startup voltage higher than the normal UVLO value. If left floating, the EN pin will be pulled up to roughly 5V by the internal 1.3 $\mu$ A current source. It can be driven from standard logic signals greater than 2.5V, or driven with open-drain logic to provide digital on/off control.

## Thermal Shutdown

The ACT2103 disables switching when its junction temperature exceeds 160°C and resumes when the temperature has dropped by 30°C.

## APPLICATIONS INFORMATION

### Output Voltage Setting

Figure 1:

#### Output Voltage Setting

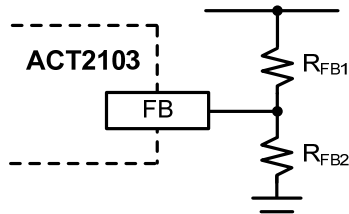


Figure 1 shows the connections for setting the output voltage. Select the proper ratio of the two feedback resistors  $R_{FB1}$  and  $R_{FB2}$  based on the output voltage. Typically, use  $R_{FB2} \approx 10k\Omega$  and determine  $R_{FB1}$  from the following equation:

$$R_{FB1} = R_{FB2} \left( \frac{V_{OUT}}{0.923 V} - 1 \right) \quad (1)$$

Table 1:

#### Recommended Resistance Values

$V_{OUT}$	R1	R2
5.0V	47k $\Omega$	10.5k $\Omega$
3.3V	27.4k $\Omega$	10.5k $\Omega$
2.5V	18k $\Omega$	10.5k $\Omega$
1.8V	10.2k $\Omega$	10.5k $\Omega$
1.2V	3.3k $\Omega$	10.5k $\Omega$
1.0V	1k $\Omega$	10.5k $\Omega$

### Inductor Selection

The inductor maintains a continuous current to the

Table 2:

#### Inductor Values Range and Typical Compensation

$V_{OUT}$	$V_{IN}$	L	$C_{OUT}$	$R_{COMP}$	$C_{COMP}$	$C_{COMP2}$
5.0V	7V ~ 18V	10 $\mu$ H ~ 22 $\mu$ H	330 $\mu$ F/10V	25k $\Omega$	2.2nF	220PF
			22 $\mu$ F/ Ceramic $\times$ 2	10k $\Omega$	2.2nF	N/A
3.3V	5V ~ 18V	8.2 $\mu$ H ~ 15 $\mu$ H	330 $\mu$ F/10V	21k $\Omega$	2.2nF	220PF
			22 $\mu$ F/ Ceramic $\times$ 2	8.2k $\Omega$	2.2nF	N/A
1.8V	4.5V ~ 18V	3.3 $\mu$ H ~ 10 $\mu$ H	470 $\mu$ F/10V	12k $\Omega$	4.7nF	220PF
			22 $\mu$ F/ Ceramic $\times$ 2	8.2k $\Omega$	4.7nF	N/A
1.2V	4.5V ~ 12V	2.5 $\mu$ H ~ 9.1 $\mu$ H	470 $\mu$ F/10V	12k $\Omega$	10nF	220PF
			22 $\mu$ F/ Ceramic $\times$ 2	8.2k $\Omega$	10nF	N/A
1.0V	4.5V ~ 10V	2.2 $\mu$ H ~ 8.2 $\mu$ H	470 $\mu$ F/10V	10k $\Omega$	10nF	220PF
			22 $\mu$ F/ Ceramic $\times$ 2	8.2k $\Omega$	10nF	N/A

output load. This inductor current has a ripple that is dependent on the inductance value:

Higher inductance reduces the peak-to-peak ripple current. The trade off for high inductance value is the increase in inductor core size and series resistance, and the reduction in current handling capability. In general, select an inductance value L based on ripple current requirement:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} f_{SW} I_{LOADMAX} K_{RIPPLE}} \quad (2)$$

where  $V_{IN}$  is the input voltage,  $V_{OUT}$  is the output voltage,  $f_{SW}$  is the switching frequency,  $I_{LOADMAX}$  is the maximum load current, and  $K_{RIPPLE}$  is the ripple factor. Typically, choose  $K_{RIPPLE} = 20\sim 40\%$  to correspond to the peak-to-peak inductor ripple current being 20~40% of the maximum load current.

With a selected inductor value the peak-to-peak inductor current is estimated as:

$$I_{LPK-PK} = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{L \times V_{IN} \times f_{SW}} \quad (3)$$

The peak inductor current is estimated as:

$$I_{LPK} = I_{LOADMAX} + \frac{1}{2} I_{LPK-PK} \quad (4)$$

The selected inductor should not saturate at  $I_{LPK}$ . The maximum output current is calculated as:

$$I_{OUTMAX} = I_{LIM} - \frac{1}{2} I_{LPK-PK} \quad (5)$$

$I_{LIM}$  is the internal current limit, which is typically 4.5A, as shown in Electrical Characteristics Table.



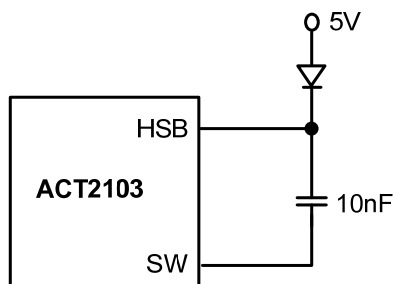
## APPLICATIONS INFORMATION CONT'D

### External High Voltage Bias Diode

It is recommended that an external High Voltage Bias diode be added when the system has a 5V fixed input or the power supply generates a 5V output. This helps improve the efficiency of the regulator. The High Voltage Bias diode can be a low cost one such as IN4148 or BAT54.

**Figure 2:**

**External High Voltage Bias Diode**



This diode is also recommended for high duty cycle operation and high output voltage applications.

### Input Capacitor

The input capacitor needs to be carefully selected to maintain sufficiently low ripple at the supply input of the converter. A low ESR capacitor is highly recommended. Since large current flows in and out of this capacitor during switching, its ESR also affects efficiency.

The input capacitance needs to be higher than 10µF. The best choice is the ceramic type, however, low ESR tantalum or electrolytic types may also be used provided that the RMS ripple current rating is higher than 50% of the output current. The input capacitor should be placed close to the IN and G pins of the IC, with the shortest traces possible. In the case of tantalum or electrolytic types, they can be further away if a small parallel 0.1µF ceramic capacitor is placed right next to the IC.

### Output Capacitor

The output capacitor also needs to have low ESR to keep low output voltage ripple. The output ripple voltage is:

$$V_{RIPPLE} = I_{OUTMAX} K_{RIPPLE} R_{ESR} + \frac{V_{IN}}{28 \times f_{SW}^2 LC_{OUT}} \quad (6)$$

where  $I_{OUTMAX}$  is the maximum output current,  $K_{RIPPLE}$  is the ripple factor,  $R_{ESR}$  is the ESR of the output capacitor,  $f_{SW}$  is the switching frequency,  $L$  is the inductor value, and  $C_{OUT}$  is the output capacitance.

In the case of ceramic output capacitors,  $R_{ESR}$  is very small and does not contribute to the ripple. Therefore, a lower capacitance value can be used for ceramic type. In the case of tantalum or electrolytic capacitors, the ripple is dominated by  $R_{ESR}$  multiplied by the ripple current. In that case, the output capacitor is chosen to have sufficiently low ESR.

For ceramic output capacitor, typically choose a capacitance of about 22µF. For tantalum or electrolytic capacitors, choose a capacitor with less than 50mΩ ESR.

### Optional Schottky Diode

During the transition between high-side switch and low-side switch, the body diode of the low-side power MOSFET conducts the inductor current. The forward voltage of this body diode is high. An optional Schottky diode may be paralleled between the SW pin and GND pin to improve overall efficiency.

## PC Board Layout Guidance

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the IC.

- 1) Arrange the power components to reduce both the AC loop and DC loop size. AC loop includes input cap,  $V_{IN}$  pin and  $V_{IN}$  ground pin, DC loop includes SW pin, inductor, output capacitor and ground pin.
- 2) Place input decoupling ceramic capacitor  $C_{IN}$  as close to IN pin as possible.  $C_{IN}$  is connected power GND with vias or short and wide path.
- 3) Return FB, COMP and ISET to signal GND pin, and connect the signal GND to power GND at a single point for best noise immunity.
- 4) Use copper plane for power GND for best heat dissipation and noise immunity.
- 5) Place feedback resistor close to FB pin.
- 6) Use short trace connecting HSB- $C_{HSB}$ -SW loop

Figure 3 shows an example of PCB layout.

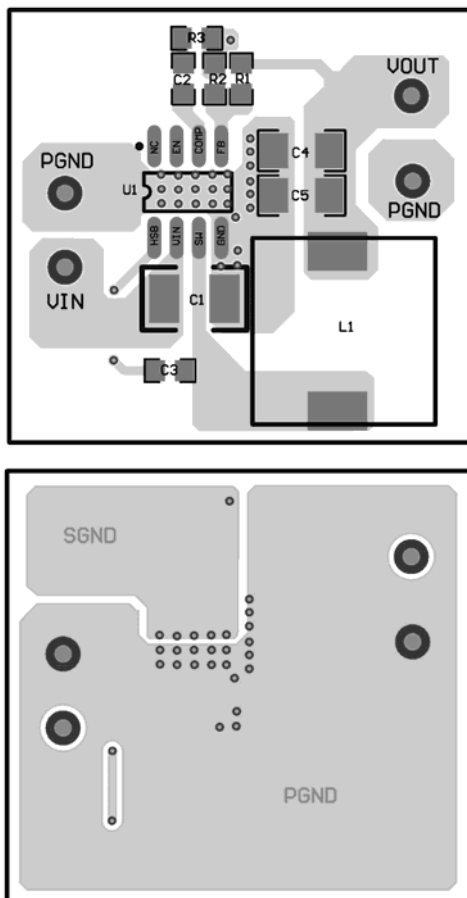
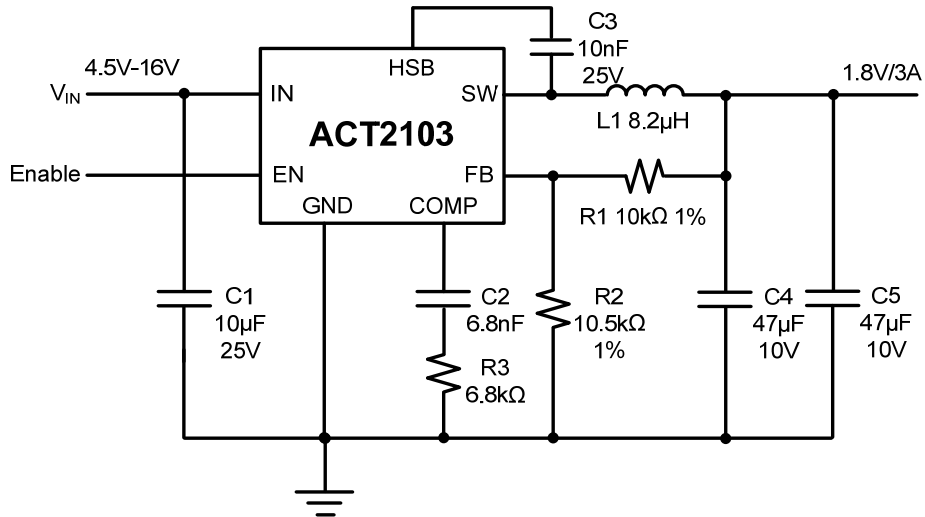


Figure 3: PCB Layout

Figure 4 and Figure 5 give two typical car charger application schematics and associated BOM list.

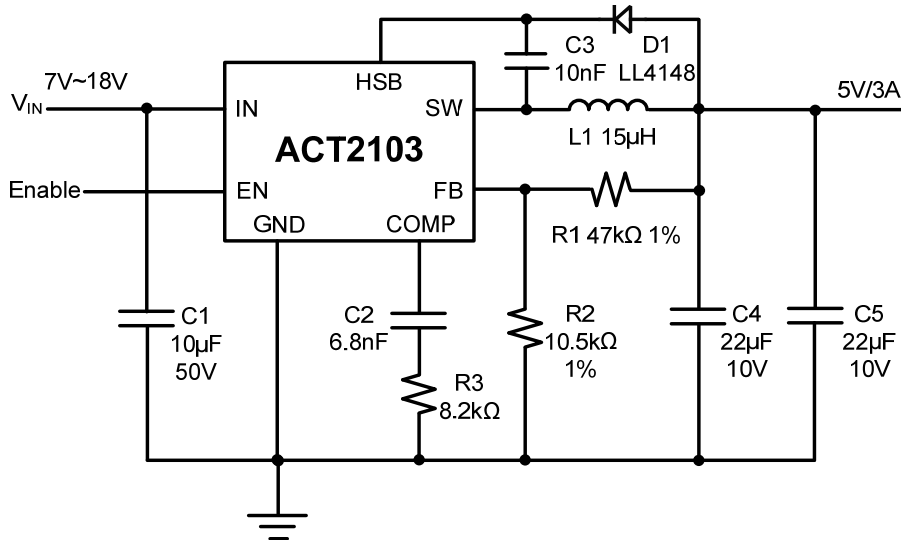
**Figure 4:**  
**Typical Application Circuit for 1.8V/3A DC-DC Converter**



**Table 3:**  
**BOM List for 1.8V/3A DC-DC Converter**

ITEM	REFERENCE	DESCRIPTION	MANUFACTURER	QTY
1	U1	IC, ACT2103YH, SOP-8EP	Active-Semi	1
2	C1	Capacitor, Ceramic, 10µF/25V, 1210, SMD	Murata, TDK	1
3	C2	Capacitor, Ceramic, 6.8nF/6.3V, 0603, SMD	Murata, TDK	1
4	C3	Capacitor, Ceramic, 10nF/25V, 0603, SMD	Murata, TDK	1
5	C4,C5	Capacitor, Ceramic, 47µF/10V, 1206, SMD	Murata, TDK	2
6	L1	Inductor, 8.2µH, 4A, 20%, SMD	Tyco Electronics	1
7	R1	Chip Resistor, 10kΩ, 0603, 1%	Murata, TDK	1
8	R2	Chip Resistor, 10.5kΩ, 0603, 1%	Murata, TDK	1
9	R3	Chip Resistor, 6.8kΩ, 0603, 5%	Murata, TDK	1

**Figure 5:**  
**Typical Application Circuit for 5V/3A DC-DC Converter**

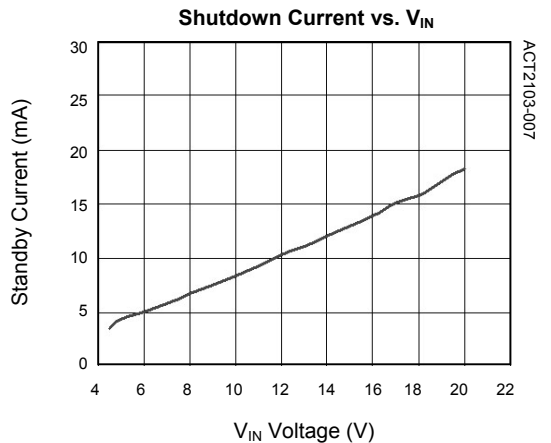
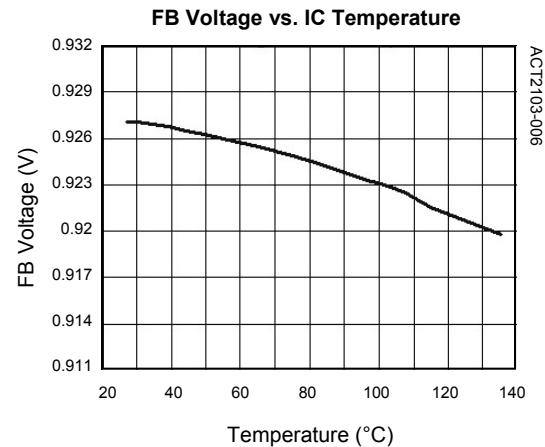
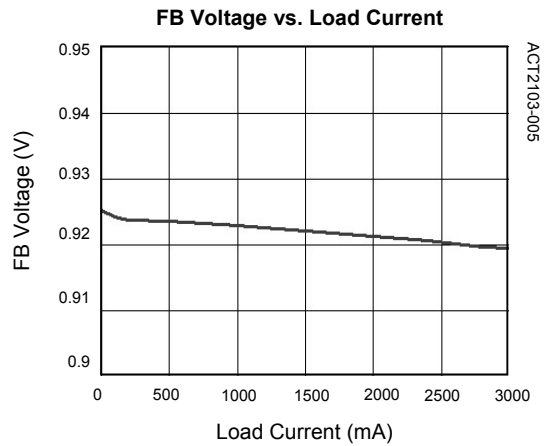
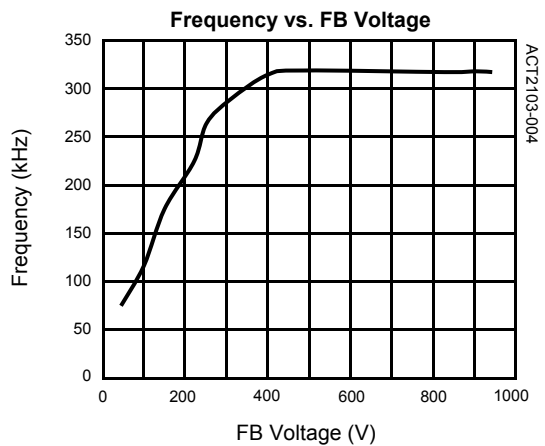
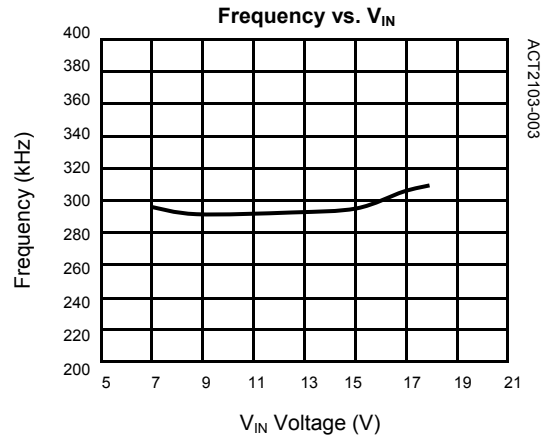
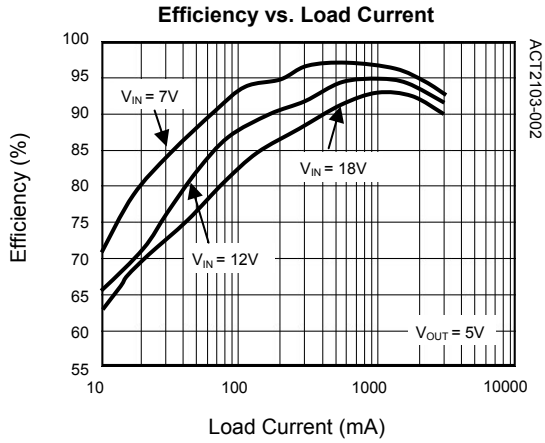


**Table 4:**  
**BOM List for 5V/3A DC-DC Converter**

ITEM	REFERENCE	DESCRIPTION	MANUFACTURER	QTY
1	U1	IC, ACT2103YH, SOP-8EP	Active-Semi	1
2	C1	Capacitor, Ceramic, 10µF/50V, 1210, SMD	Murata, TDK	1
3	C2	Capacitor, Ceramic, 6.8nF/6.3V, 0603, SMD	Murata, TDK	1
4	C3	Capacitor, Ceramic, 10nF/50V, 0603, SMD	Murata, TDK	1
5	C4,C5	Capacitor, Ceramic, 22µF/10V, 1206, SMD	Murata, TDK	2
6	L1	Inductor, 15µH, 4A, 20%	Sumida	1
7	D1	Diode, 75V/150mA, LL4148	Good-ARK	1
8	R1	Chip Resistor, 47kΩ, 0603, 1%	Murata, TDK	1
9	R2	Chip Resistor, 10.5kΩ, 0603, 1%	Murata, TDK	1
10	R3	Chip Resistor, 8.2kΩ, 0603, 5%	Murata, TDK	1

## TYPICAL PERFORMANCE CHARACTERISTICS

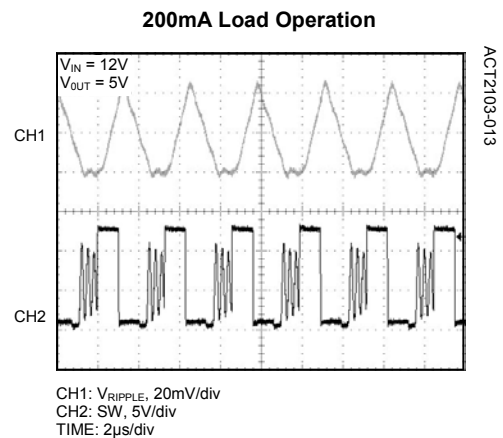
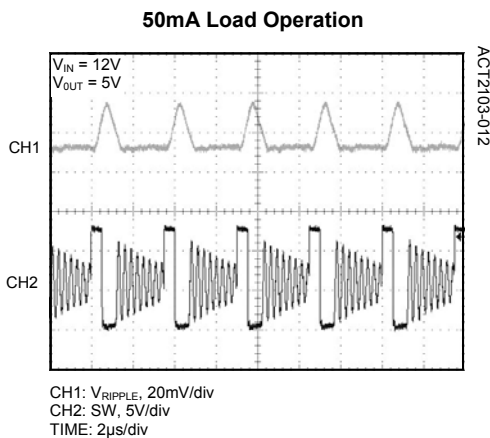
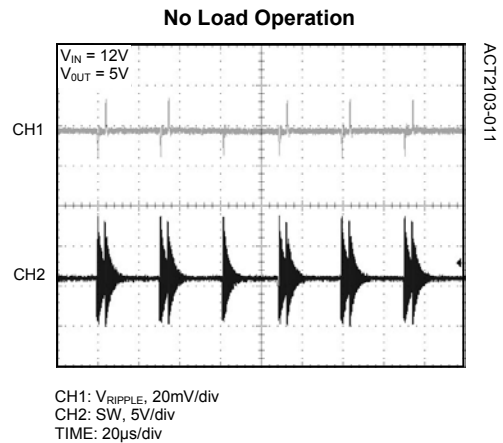
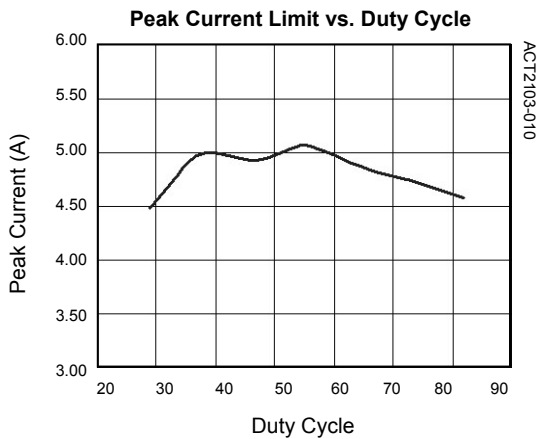
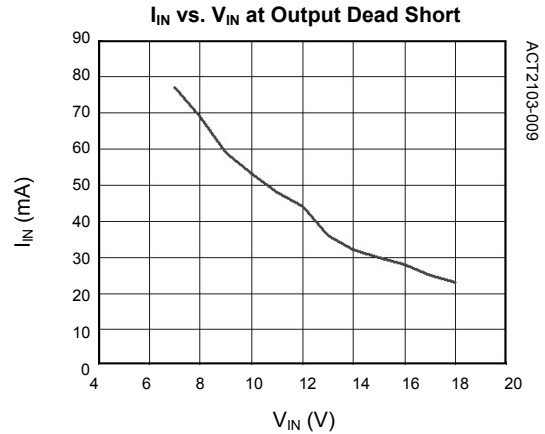
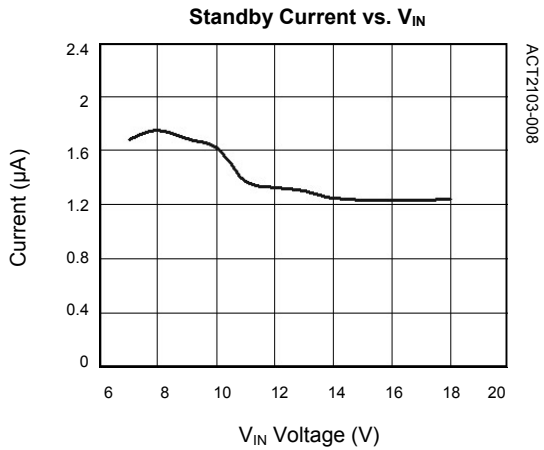
(L = 15μH, C<sub>IN</sub> = 100μF, C<sub>OUT</sub> = 330μF, T<sub>a</sub> = 25°C, R<sub>COMP</sub> = 18k, C<sub>COMP1</sub> = 2.2nF, C<sub>COMP2</sub> = N/C)





## TYPICAL PERFORMANCE CHARACTERISTICS

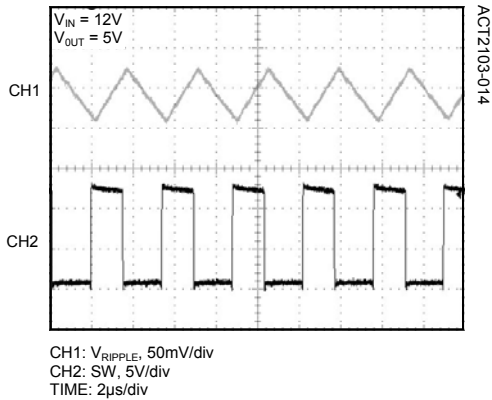
(L = 15μH, C<sub>IN</sub> = 100μF, C<sub>OUT</sub> = 330μF, Ta = 25°C, R<sub>COMP</sub> = 18k, C<sub>COMP1</sub> = 2.2nF, C<sub>COMP2</sub> = N/C)



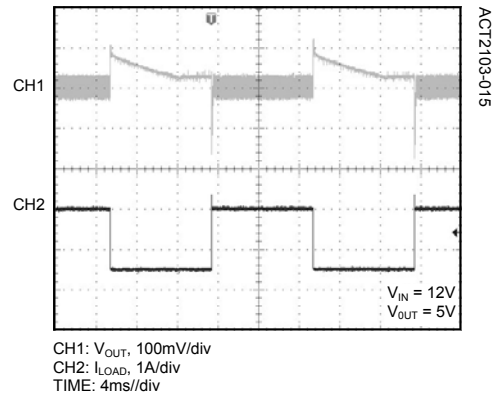
## TYPICAL PERFORMANCE CHARACTERISTICS

(L = 15 $\mu$ H, C<sub>IN</sub> = 100 $\mu$ F, C<sub>OUT</sub> = 330 $\mu$ F, Ta = 25°C, R<sub>COMP</sub> = 18k, C<sub>COMP1</sub> = 2.2nF, C<sub>COMP2</sub> = N/C)

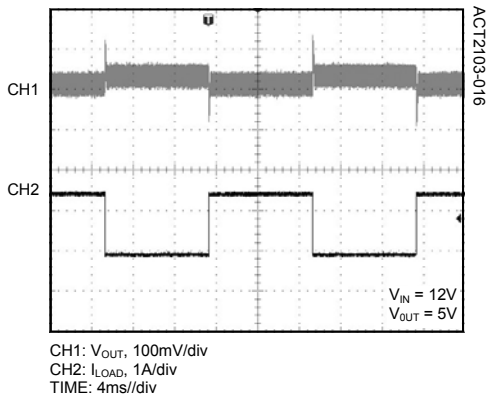
### 3A Load Operation



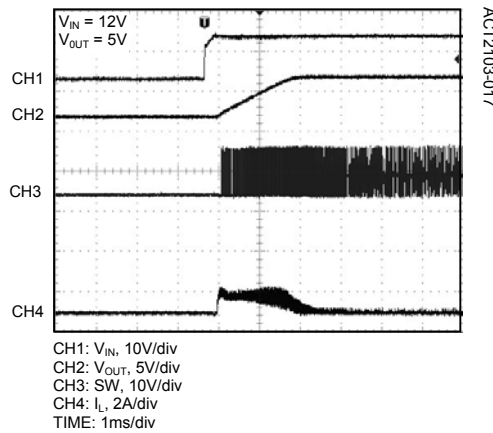
### Load Transient (0A~1.5A)



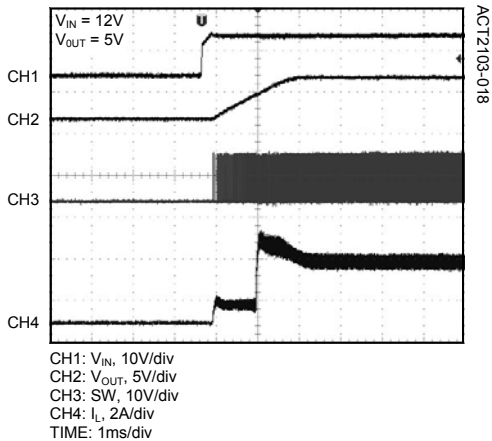
### Load Transient (1.5A~3A)



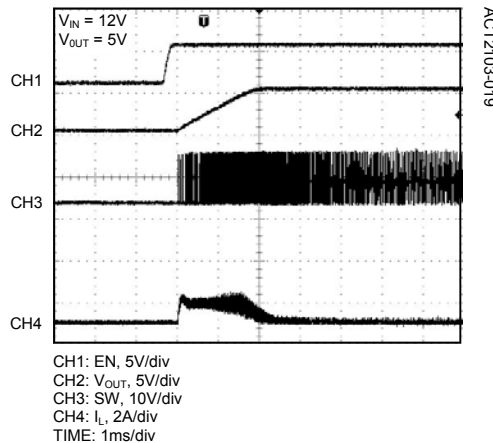
### Start Up with V<sub>IN</sub> (Load 0A)



### Start Up with V<sub>IN</sub> (Load 3A)



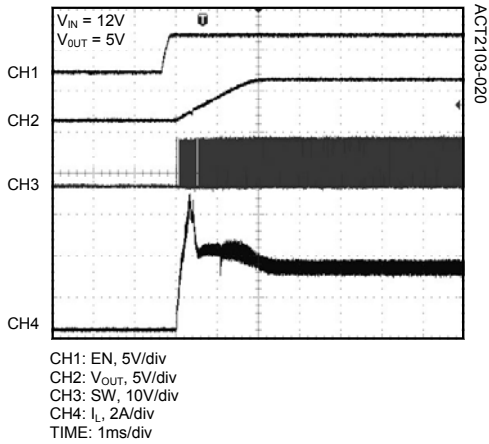
### Start Up with EN (Load 0A)



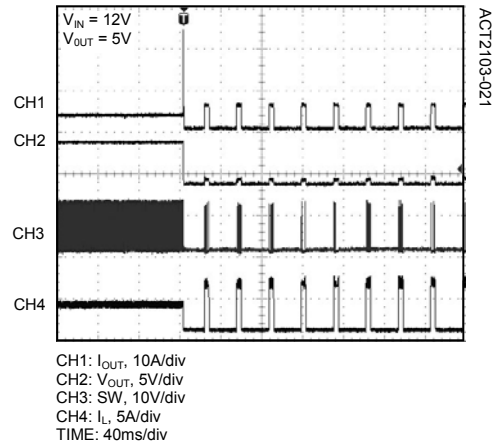
## TYPICAL PERFORMANCE CHARACTERISTICS

(L = 15 $\mu$ H, C<sub>IN</sub> = 100 $\mu$ F, C<sub>OUT</sub> = 330 $\mu$ F, T<sub>a</sub> = 25°C, R<sub>COMP</sub> = 18k, C<sub>COMP1</sub> = 2.2nF, C<sub>COMP2</sub> = N/C)

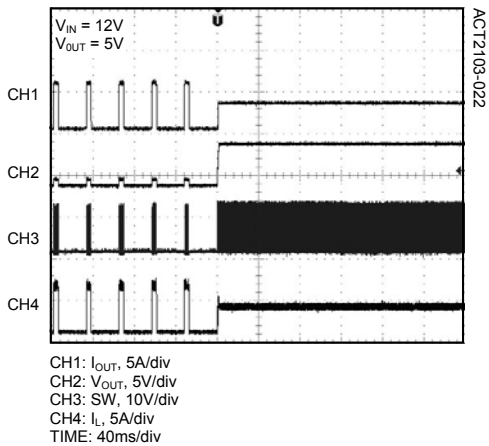
**Start Up with EN (Load 3A)**



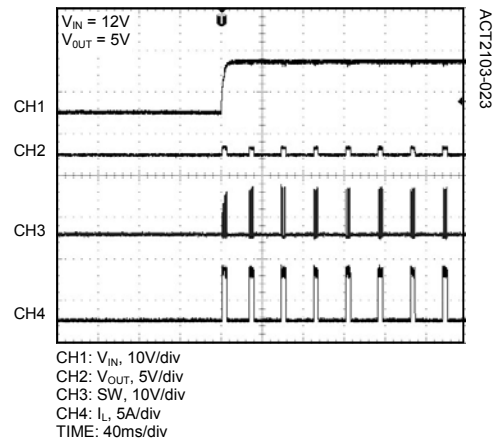
**Short Circuit**



**Short Circuit Recovery**

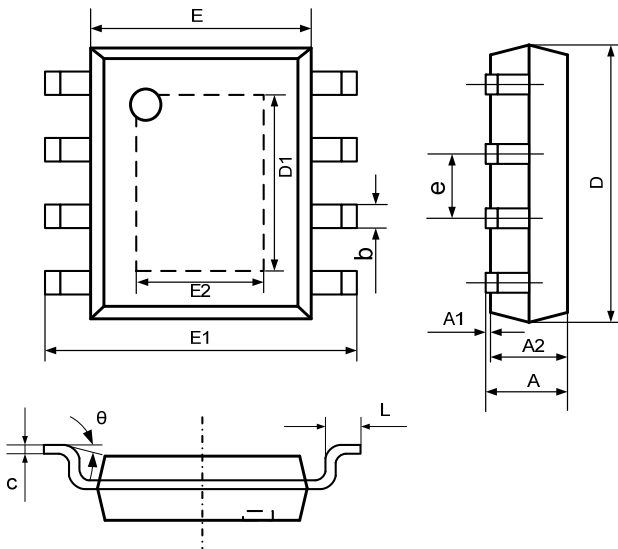


**Start Up with Output Dead Short**



## PACKAGE OUTLINE

### SOP-8EP PACKAGE OUTLINE AND DIMENSIONS



SYMBOL	DIMENSION IN MILLIMETERS		DIMENSION IN INCHES	
	MIN	MAX	MIN	MAX
A	1.350	1.700	0.053	0.067
A1	0.000	0.100	0.000	0.004
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.200
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
E2	2.313	2.513	0.091	0.099
e	1.270 TYP		0.050 TYP	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

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